

RoHS & Halogen Free & REACH Compliance.

Drawing No			QC01	0241104	622	
Quantity	X	Pcs.	Date		2024/11/08	
Pulse P/N			MHCI06	6040-3R3	M-R8	
			FICATION]
COMPONENT		ACCE	PTED BY			4
ENGINEER						
ELECTRICAL						1
ENGINEER						
MECHANICAL						
ENGINEER						4
APPROVED						
REJECTED						
Chilisin Electronics C No. 270, Nanfeng Rd., Pir City 324019, Taiwan (R.O Tel: +886-3-415-9111	ngzhen Dis	t., Taoyuan	No. 78, Pu Qingxi Tov	ıxing Rd., Yuli	(Dongguan) Co., Ltd. iangwei Administration Area, n City, Guangdong,China 51~3	
Chilisin Electronics (No 143 - 145, Road No 10 Lap Le Commune, Thuy N Haiphong City, Vietnam Tel: 84-316 255 688), VSIP Ha	i Phong,	Ltd No. 8, Sha Huaihua C	ıziao Liangshı	etronics Technology Co., uijing Town, Yuanling County, ovince 419601, China	
Chilisin Electronics (I No. 240, Binjiang South R Kunshan City, Jiangsu Pro Tel: 0512-57450881	oad, Zhan	Limited gpu Town,				

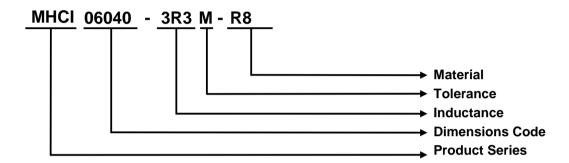


Revisions

Rev.	Description	Date	Approved by	Checked by	Drawn by
01	Initial release	2024/11/08	Mark Chung	Wayne Wu	Ryan Tsai



- **1** Scope This specification applies to large current and low loss SMD power inductor.
- 2 Part numbering

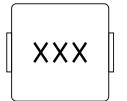


3 Temperature rating

Operating Temperature: -55°C to 125°C.

Storage Temperature: (on tape & reel): -20°C to +40°C; 75% RH max.

4 Marking



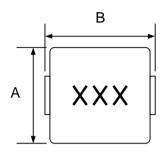
Marking: 3R3

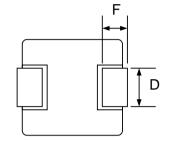
5 Standard testing condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH



6 Configuration and dimensions





Dimensions in mm

Type	06040
Α	6.6 ± 0.2
В	7.5 Max
С	4.0 Max
D	2.9 Typ
F	1.6 ± 0.5



Size Code	Net weight(grms)
06040	1.0(typ.)

7 Electrical characteristics

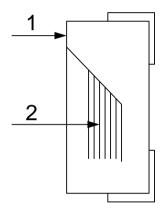
Part number	Inductance (uH)	Tolerance (±%)	Test Freq.	Irms (A) Typ.	Isat (A) Typ.	RDC (mΩ) ±10%	Marking
MHCI06040-3R3M-R8	3.3	20	100kHz,0.5V	10	13	16	3R3

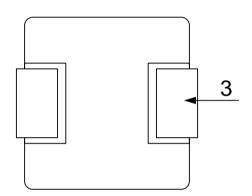
Note:

- 1. Operating temperature range -55°C to 125°C.
- 2. Isat for Inductance drop 30% from its value without current.
- 3. Irms for a 40°C temperature rise from 25°C ambient.
- 4. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design 125°C under worst case operating conditions. Component placement, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
- 5. Absolute maximum voltage 30V DC. (Based on test method, it may not the sameunder different application, it is recommended to verify first.)



MHCI06040 Series 8.1 Construction





8.2 Material List

Item	Part	Description
1	Magnetic core	Magnetic metal powder
2	Coil	Enameled copper wire
3	Terminals	Copper based terminal



9 Reliability test items

1-1.Mechanical Performance

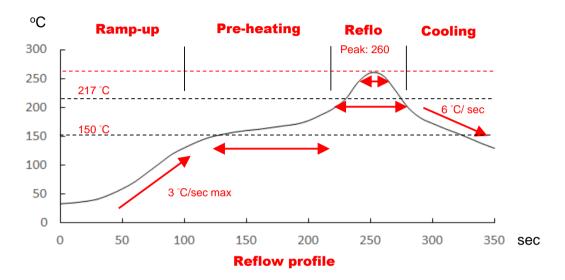
No	Item	Specification	Test Method
1-1-1	Vibration	Appearance: No damage	Test device shall be soldered on the substrate
		Inductance:within±10% of	Oscillation Frequency: 10 to 55 to 10Hz for 1min
		initial value	Amplitude: 1.5mm
			Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-2	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150°C, 1min
			Solder Composition: Sn/Ag3.0/Cu0.5
			Solder Temperature: 260±5°C
			Immersion Time: 10±1sec
1-1-3	Solder ability	The electrodes shall be at	Pre-heating: 150°C, 1min
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5
		solder coating	Solder Temperature: 245±5°C
			Immersion Time: 4±1sec
1-1-4	Resistance to solvent	There must be no change in	Inductors must withstand 6 minutes of alcohol or water.
		appearance or obliteration of	
		marking.	

1-2.Environmental Performance

No	Item	Specification		Test Method		
1-2-1	Temperature Shock	Appearance: No damage	10 cycles (Air to Air) 1 cycles shall consis	st of:	
		Inductance:within±10% of	30 minutes exposure to -55°C			
		initial value	30 minutes exposure to 125°C			
			15 second	s maximum transition between	temperatures	
1-2-2	Temperature Cycle	7	One cycle:			
			Step	Temperature (°C)	Time (min)	
			1	-55±3	30	
			2	25±2	3	
			3	125±3	30	
			4	25±2	3	
			Total: 100cycles			
			Measured	after exposure in the room cor	ndition for 24hrs	
1-2-3	Humidity Resistance		Temperature: 40±2°C			
			Relative Humidity: 90 ~ 95%			
			Time: 1000hrs			
			Measured after exposure in the room condition for 24hrs			
1-2-4	Heat Life		Temperature: 85±3°C			
				umidity: 20%		
			Applied Cu	irrent: Rated Current		
			Time: 1000hrs			
			Measured after exposure in the room condition for 24hrs			
1-2-5	Cold Resistance		Temperature: -55±3°C			
			Relative H	umidity: 0%		
			Time: 1000	Ohrs		
			Measured	after exposure in the room cor	ndition for 24hrs	



10 Recommended IR reflow profile



Lead-Free(LF) Refer to J-STD-020C

Item	Ramp-up	Pre-heating	Reflow	Peak Temp.	Cooling
Temp. scope	R.T. ~150 °C	150 °C~200 °C	217 °C	260±5 °C	Peak Temp. 150 °C
Time spec	-	60~180 sec	60~150 sec	20~40 sec	-
Time result	-	75~100 sec	90~120 sec	20~35 sec	-

Note:

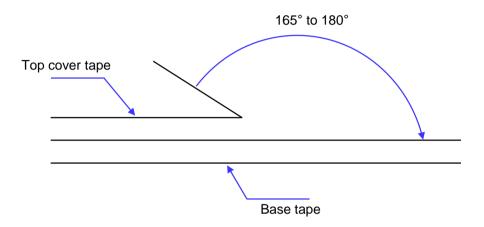
- 1. IR reflow times: within 3 times.
- 2. Nitrogen adopted is recommended while in IR reflow.



11 Packaging

11.1 Packaging-cover tape

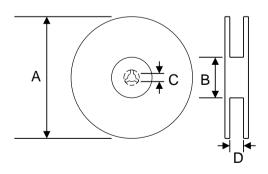
The force for tearing off cover tape is 10 to 130 grams.



11.2 Packaging quantity

Type	pcs/reel
06040	1000

11.3 Reel dimensions



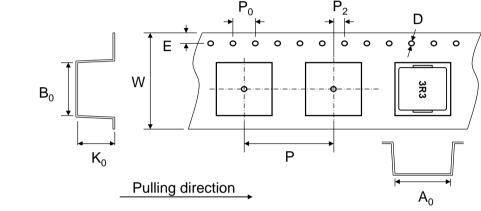
Dimensions in mm

Туре	Α	В	С	D
06040	330	100	13	16



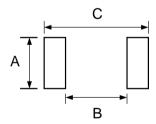
11 Packaging

11.4 Tape dimensions in mm



Type	A_0	B_{0}	K_0	D	Е	W	Р	P ₀	P_2
06040	6.9	7.6	4.25	1.5	1.75	16	12	4	2

12 Recommended pattern



-			
1)ıma	ensions	ın	mm
	,	- 11 1	

Type	Α	В	C
06040	3.5	3.7	8.4

13 Note

- 1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Don't design/ mount any components in contact with this product.
- 3. The moisture sensitivity level (MSL) of products is classified as level 1.
- 4. Shelf life: 1 years from the date of shipment.





